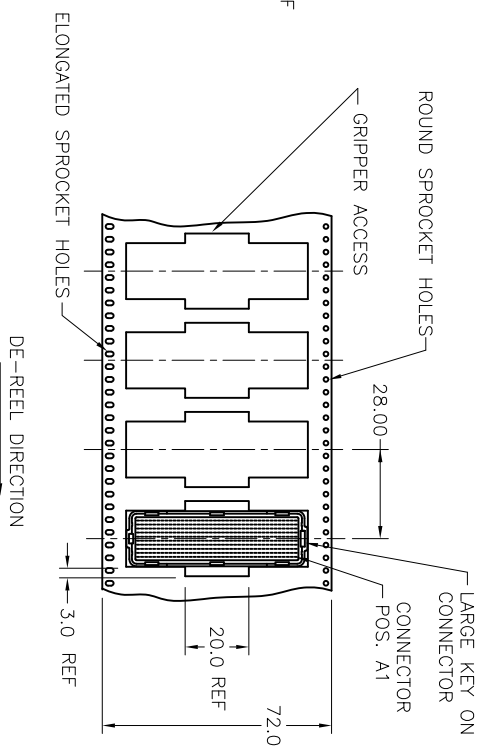
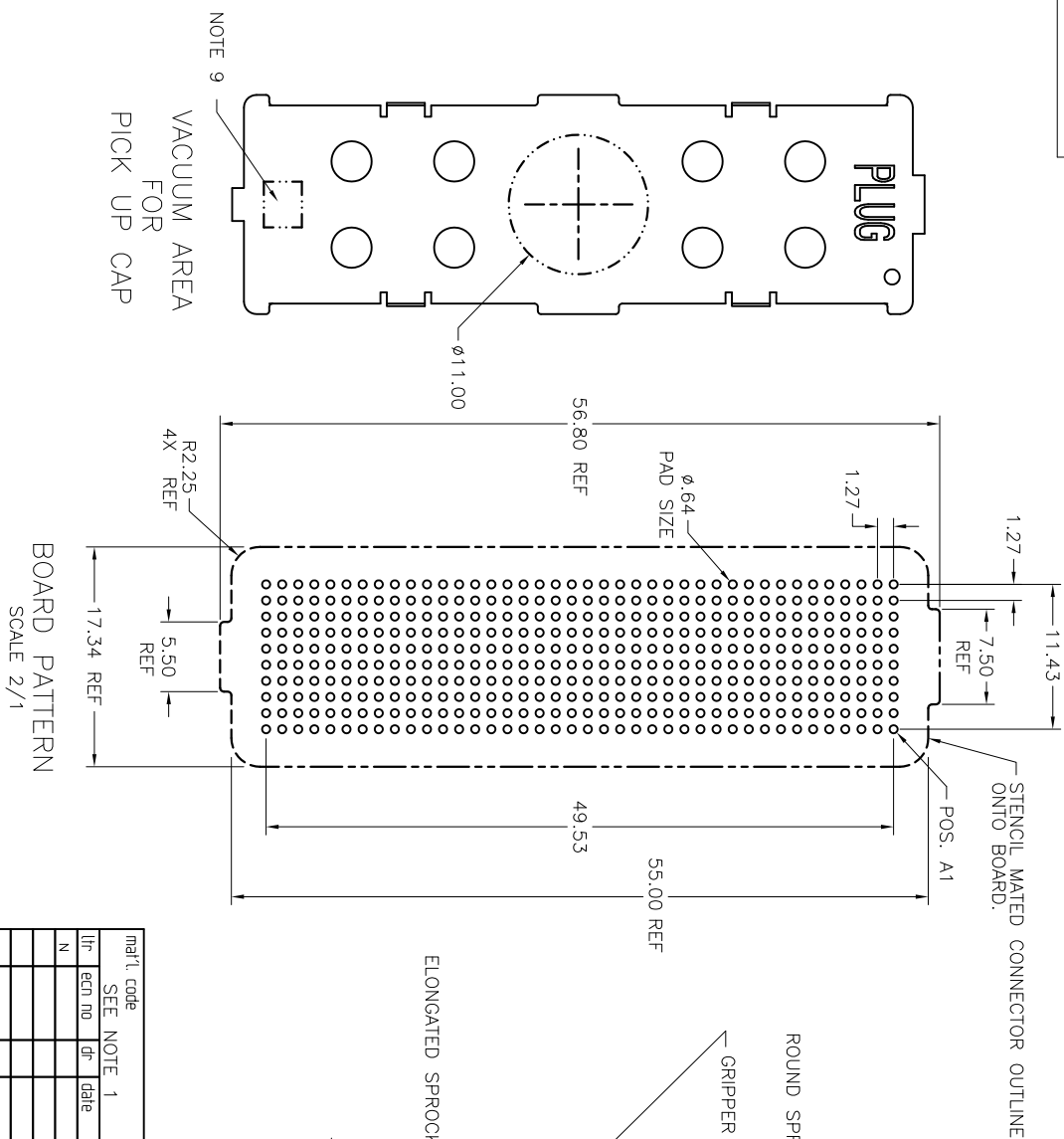


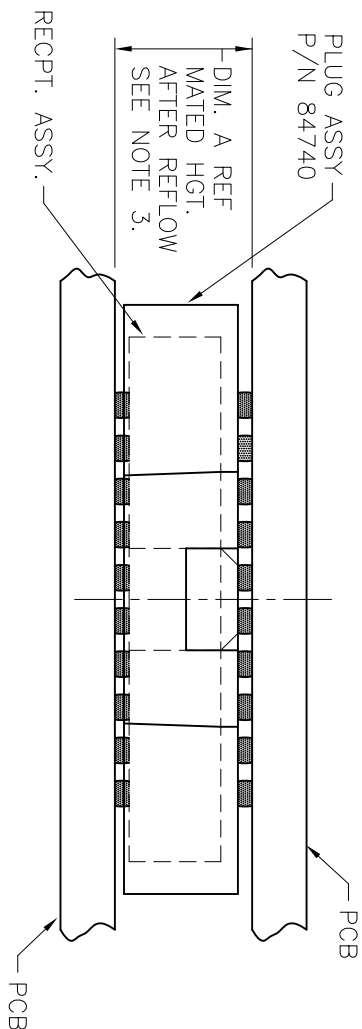
PRODUCT NUMBER
SEE TABLE



TAPE & REEL PACKAGING SCALE NONE
PER EIA 481-3

mat'l. code		surface		tolerance		projection		
SEE NOTE 1		ASME Y14.5 ✓		ASME Y14.5				
lfr	ecrn no.	dfr	date	inferences unless otherwise specified				
N				X .+3 angles  .XX +.3				
				XXX -.051				
		OT ±.21		scale 2:1				
		D. WALSHEN	1998-09-18					
		M. HAHN	1998-09-18					
		CHE	1998-09-18					
		M. HAHN	1998-09-18					
		apnd	M. HAHN	1998-09-18				
sheet index	revision	sheet						
product family				title				
MEG--ARRAY				0mm PLUG ASSEMBLY				
				10 x 40 = 400 POSITIONS				
dwg no				sheet 2 of 4				
84740				size A4				
CUSTOMER Drawing								

PRODUCT NUMBER
SEE TABLE



MATED HEIGHT TABLE	
DIM. A	RECEPT. ASSY. P/N
4.0	74221
6.0	74388
8.0	74390

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW – MATED CONNECTORS SCALE NONE

mat'l. code		SEE NOTE 1		surface		tolerance		projection		product family	
lbr	ecn no	dtr	date	ASPC Y4.5	ASPC Y4.5	ASPC Y4.5	ASPC Y4.5	ASPC Y4.5	ASPC Y4.5	MEG-ARRAY	
N				angles	mm	X .43	XX .18	XXX .051	Scale 2:1	0mm PLUG ASSEMBLY	
				dtr	D. WAUGHEN	1998-09-18				10 x 40 = 400 POSITIONS	
				engr	M. HAHN	1998-09-18					
				cltr	M. HAHN	1998-09-18					
				apdd	M. HAHN	1998-09-18					
sheet	revision										
index	sheet										

NOTES:

A

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS WITH LEADED OR SOME SOLDERING APPLICATIONS.

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